

Technical Data Sheet

Epo-Tek H22 Adhesive

#12673-22

Epo-Tek H22 Adhesive is a two-component, silver-filled epoxy system made for die bonding and sealing hybrid circuit packages.

Technical Information

Composition Properties

Number of components	Two
Mix ratio by weight	100:4.5
Specific gravity	Part A: 2.03 Part B: 1.03
Pot Life	16 hours
Shelf Life	Six months at room temperature

Minimum Bond Line Cure Schedule

150°C	5 minutes
120°C	10 minutes
100°C	20 minutes

Please note that containers should be kept close when they are not being used. For filled systems, we recommend mixing the contents of container A and B very well before combining them.